



Dual Rail-to-Rail I/O, High-Slew-Rate OP Amp

Features

- +3V to +5.5V Single-Supply Operation
- Input / Output Rail-to-Rail
- Low input current
- High output driving capacity
- Low Quiescent Current: 1mA @ 5V
- High Slew rate 6.5V/ μ s
- High Gain-Bandwidth Product 6.5MHz
- High Open Loop Gain 95dB
- High PSRR 70dB

Applications

- Headphone Driver
- Portable Equipment
- Battery-Powered Equipment
- Multimedia Audio
- ASIC Input or Output Amplifier
- Sensor Amplifier
- Low Power/Low Voltage Applications

General Description

G1224 is a input/output rail-to-rail Operational Amplifier. It can be operated from +3V to +5.5V single supply or from $\pm 1.5V$ to ± 2.75 dual supply. G1224 can drive 66mA into resistor loads to within 10% power rail each amplifier. AC performance is very excellent with 6.5MHz bandwidth, 6.5V/ μ s Slew Rate, 95dB open loop gain, 60 degree phase margin and low distortion.

Supply current of G1224 is only 500 μ A per Amplifier. It is very suitable for low current consumption applications to control high current loads. Applications include audio amplification for computers, sound ports, sound cards and set-top boxes.

G1224 is available in 8pins SOP8, MSOP 8.

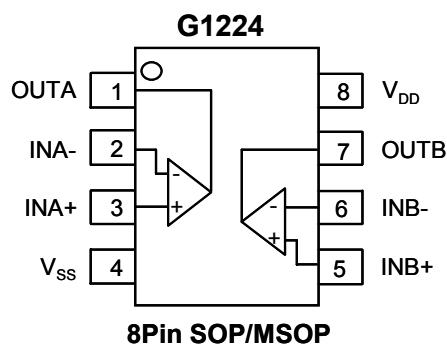
Ordering Information

PART NUMBER	MARKING	TEMP. RANGE	PIN-PACKAGE
G1224P1X	G1224	0°C to 85°C	SOP 8L
G1224P8X	G1224	0°C to 85°C	MSOP 8L

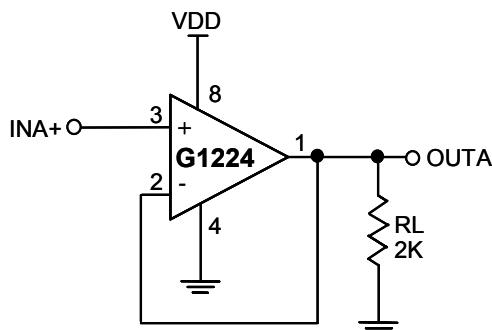
Note: X Specify the packing type

U: Tape & Reel T: Tube

Pin Configuration



Typical Application Circuit



**Absolute Maximum Ratings**

Supply Voltage (V_{DD} to V_{SS}).....	6.5V	θ_{JA}	240°C/Watt
All Other Pins.....	(V_{SS} -0.3V) to (V_{DD} +0.3V)	Junction Temperature.....	150°C
Continuous Power Dissipation ($T_A=25^\circ C$)		Operating Temperature Range.....	0°C to 85°C
SOP 8.....	520mW	Storage Temperature Range.....	-65°C to 160°C
MSOP8.....	520mW	Lead Temperature (soldering, 10sec).....	260°C

Electrical Characteristics

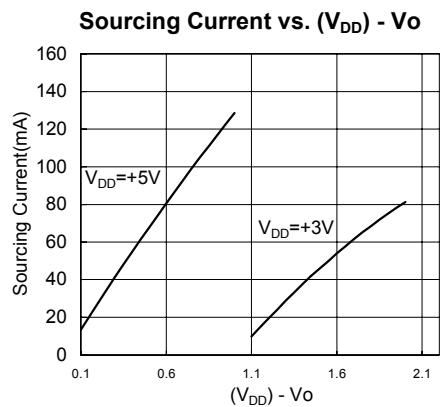
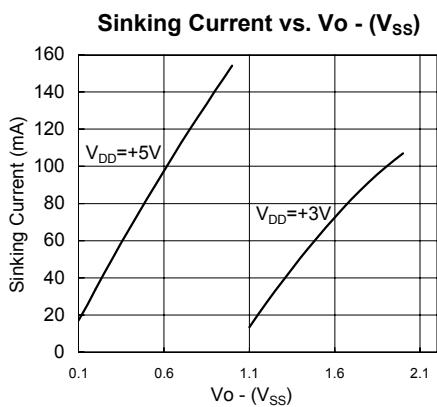
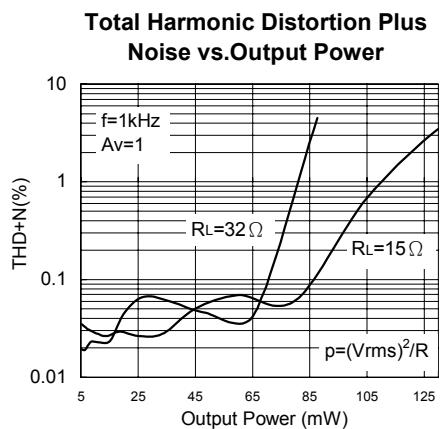
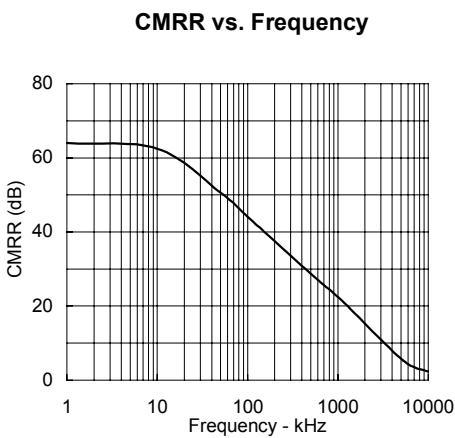
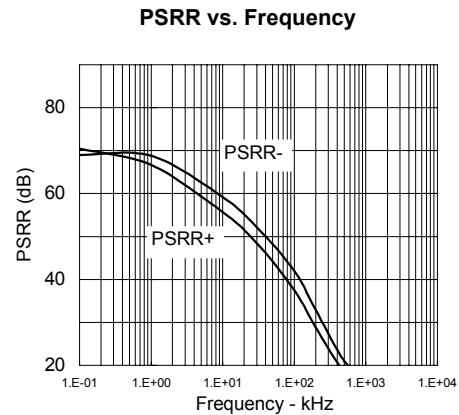
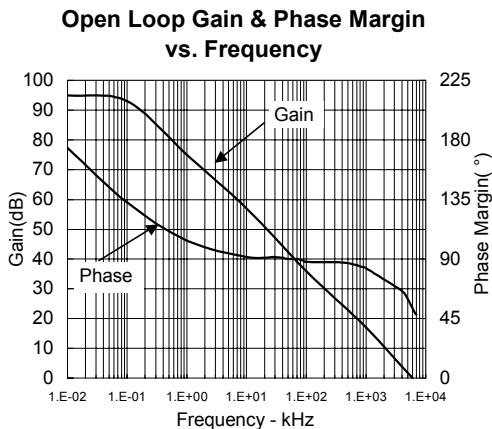
$V_{DD} = 5V$; $V_{SS} = 0V$; $T_{amb} = 25^\circ C$; $C_L=10pF$, $R_L=1k\Omega$ to $V_{DD}/2$; unless otherwise specified.

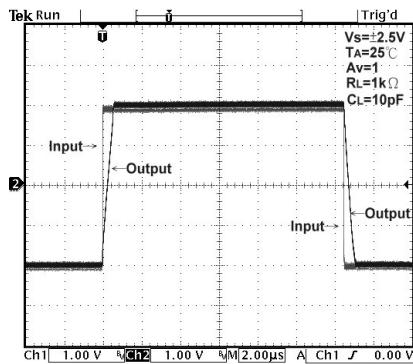
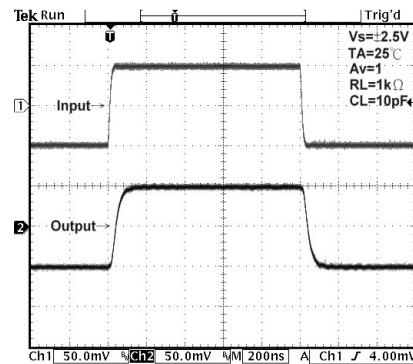
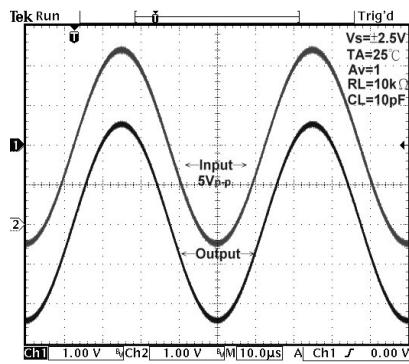
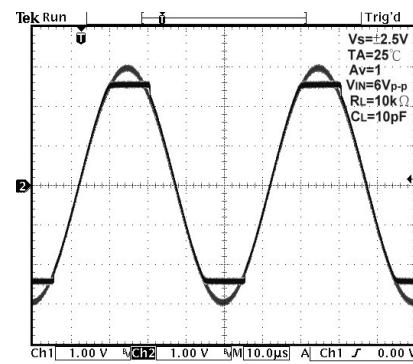
PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supplies						
Supply Voltage Range	V_{DD}	Note1	3		5.5	V
Supply Current	I_{DD}	No load	-	1	1.4	mA
Total Power Dissipation	P_{tot}	No load	-	5	7	mW
DC Characteristics						
Input Offset Voltage	$V_{I(OS)}$			± 5	± 15	mV
Common Mode Voltage	V_{CM}	Inferred from CMRR test	0	-	5	V
Input Bias Current	I_B			± 1.5	± 5	nA
Input Bias Current Offset	I_{OS}			± 1.5	± 5	nA
Input Resistance	R_{IN}		1000	-		$M\Omega$
Open Loop Gain	A_V		85	95	-	dB
Maximum Output Current	I_O	$V_{OUT} = \pm V_{IN} \times 90\%$	55	± 66	-	mA
Output Voltage Swing High	V_{OH}	$R_L = 2k\Omega$	4.96	4.99		V
Output Voltage Swing Low	V_{OL}	$R_L = 2k\Omega$		0.012	0.04	V
Power Supply Rejection Ratio	PSRR	$3V \leq V_{DD} \leq 5.5V$	50	70	-	dB
Common-Mode Rejection Ratio	CMRR	$V_{SS} \leq V_{CM} \leq V_{DD}$	50	65	-	dB
AC Characteristics						
Gain-Bandwidth Product	GBWP	Open-loop; No Load	-	6.5	-	MHz
Slew-Rate	SR	Measured from 10% to 90% of $4V_{P-P}$ step, $R_L = 1k\Omega$, $C_L = 10pF$		6.5		V/ μ s
Phase Margin	PM		-	60	-	deg
Maximum Output Current with THD	I_O	THD < 0.1%, $R_L = 16\Omega$		100		mA
Channel Separation	CS	$f = 1KHz$ $R_L = 32\Omega$		85		dB

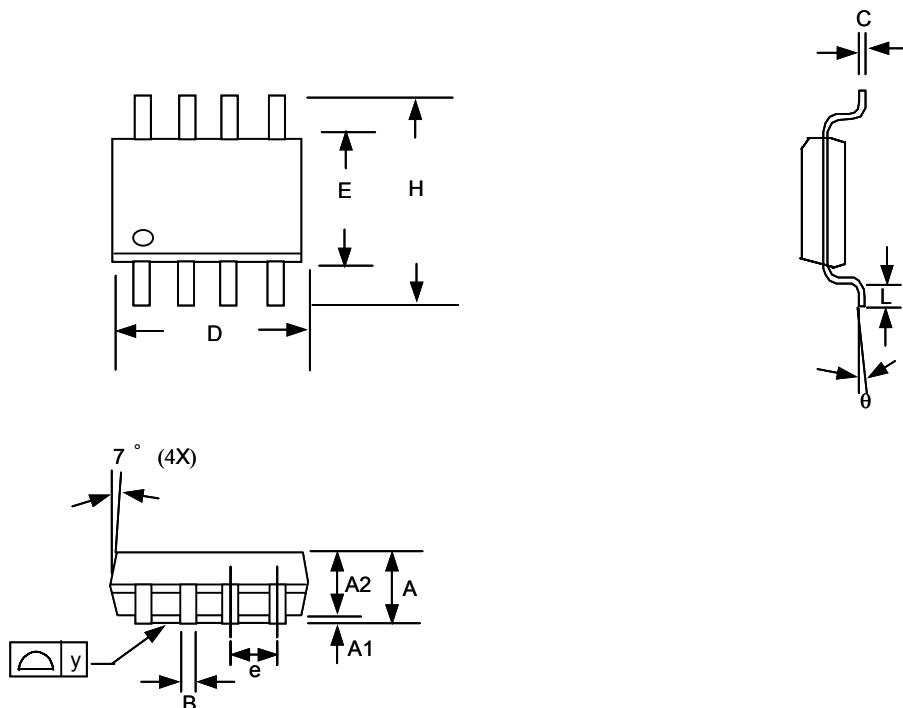
Note1: Guaranteed by the Power-Supply Rejection Ratio (PSRR) test

Typical Performance Characteristics

$V_{DD} = 5V$; $V_{SS} = 0V$; $T_{amb} = 25^\circ C$; $C_L = 10pF$, $R_L = 1k\Omega$ to $V_{DD}/2$; unless otherwise specified.

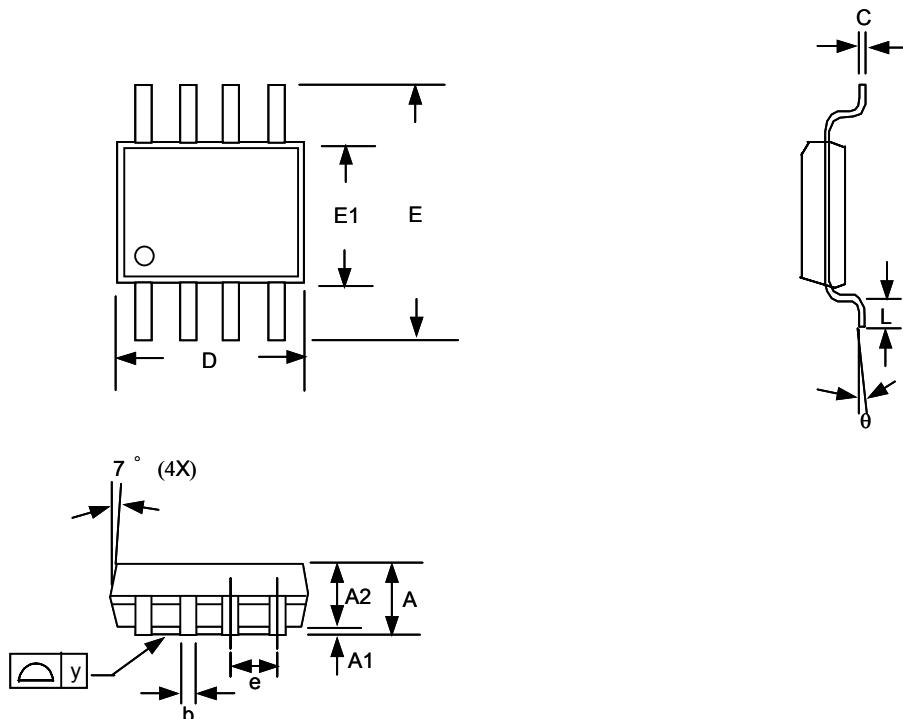


Typical Performance Characteristics (Continued)
Large Signal Transient Response

Small Signal Transient Response

Operation with Rail-to-Rail Input and Output

Operation with Beyond-the-Rail Input


Package Information

SOP- 8L Package
Note:

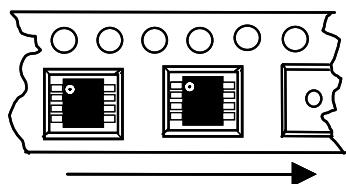
1. Package body sizes exclude mold flash and gate burrs
2. Dimension L is measured in gage plane
3. Tolerance 0.10mm unless otherwise specified
4. Controlling dimension is millimeter converted inch dimensions are not necessarily exact.
5. Followed from JEDEC MS-012

SYMBOL	DIMENSION IN MM			DIMENSION IN INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	1.35	1.60	1.75	0.053	0.063	0.069
A1	0.10	-----	0.25	0.004	-----	0.010
A2	-----	1.45	-----	-----	0.057	-----
B	0.33	-----	0.51	0.013	-----	0.020
C	0.19	-----	0.25	0.007	-----	0.010
D	4.80	-----	5.00	0.189	-----	0.197
E	3.80	-----	4.00	0.150	-----	0.157
e	-----	1.27	-----	-----	0.050	-----
H	5.80	-----	6.20	0.228	-----	0.244
L	0.40	-----	1.27	0.016	-----	0.050
y	-----	-----	0.10	-----	-----	0.004
θ	0°	-----	8°	0°	-----	8°


MSOP-8L Package
Note:

1. Package body sizes exclude mold flash and gate burrs
2. Dimension L is measured in gage plane
3. Tolerance 0.10mm unless otherwise specified
4. Controlling dimension is millimeter converted inch dimensions are not necessarily exact.
5. Followed from JEDEC MO-137

SYMBOL	DIMENSION IN MM			DIMENSION IN INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.81	1.02	1.22	0.032	0.040	0.048
A1	0.00	-----	0.20	0.000	-----	0.008
A2	0.76	0.86	0.97	0.030	0.034	0.038
b	0.28	0.30	0.38	0.011	0.012	0.015
C	0.13	0.15	0.23	0.005	0.006	0.009
D	2.90	3.00	3.10	0.114	0.118	0.122
E	4.80	4.90	5.00	0.189	0.193	0.197
E1	2.90	3.00	3.10	0.114	0.118	0.122
e	-----	0.65	-----	-----	0.026	-----
L	0.40	0.53	0.66	0.016	0.021	0.026
y	-----	-----	0.10	-----	-----	0.004
θ	0°	-----	6°	0°	-----	6°

Taping Specification

Typical SOP/MSOP Package Orientation

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